

DATA SHEET



BAS16L High-speed diode

Product specification

2003 Jun 23

High-speed diode

BAS16L

FEATURES

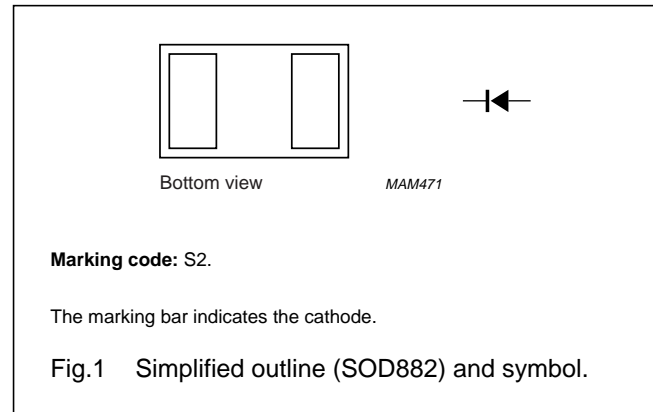
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 500 mA
- Leadless ultra small plastic package (1 mm × 0.6 mm × 0.5 mm)
- Board space 1.17 mm² (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

APPLICATIONS

- General purpose switching in surface mounted circuits
- Mobile communication, digital (still) cameras, PDA and PCMCIA cards.

DESCRIPTION

The BAS16L is a high-speed switching diode fabricated in planar technology and encapsulated in a SOD882 leadless ultra small plastic package.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	100	V
V_R	continuous reverse voltage		–	75	V
I_F	continuous forward current	see Fig.2; note 1	–	215	mA
I_{FRM}	repetitive peak forward current		–	500	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25\text{ °C}$ prior to surge; see Fig.4			
		$t = 1\ \mu\text{s}$	–	4	A
		$t = 1\ \text{ms}$	–	1	A
		$t = 1\ \text{s}$	–	0.5	A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with 60 μm copper strip line.

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ELECTRICAL CHARACTERISTICS

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_F	forward voltage	see Fig.3		
		$I_F = 1\text{ mA}$	715	mV
		$I_F = 10\text{ mA}$	855	mV
		$I_F = 50\text{ mA}$	1	V
I_R	reverse current	$I_F = 150\text{ mA}$	1.25	V
		see Fig.5		
		$V_R = 25\text{ V}$	30	nA
		$V_R = 75\text{ V}$	1	μA
C_d	diode capacitance	$V_R = 25\text{ V}; T_j = 150\text{ °C}$	30	μA
		$V_R = 75\text{ V}; T_j = 150\text{ °C}$	50	μA
C_d	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz};$ see Fig.6	1.5	pF
t_{rr}	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}; R_L = 100\ \Omega;$ measured at $I_R = 1\text{ mA};$	4	ns
V_{fr}	forward recovery voltage	when switched from $I_F = 10\text{ mA};$ $t_r = 20\text{ ns}$	1.75	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with 60 μm copper strip line.

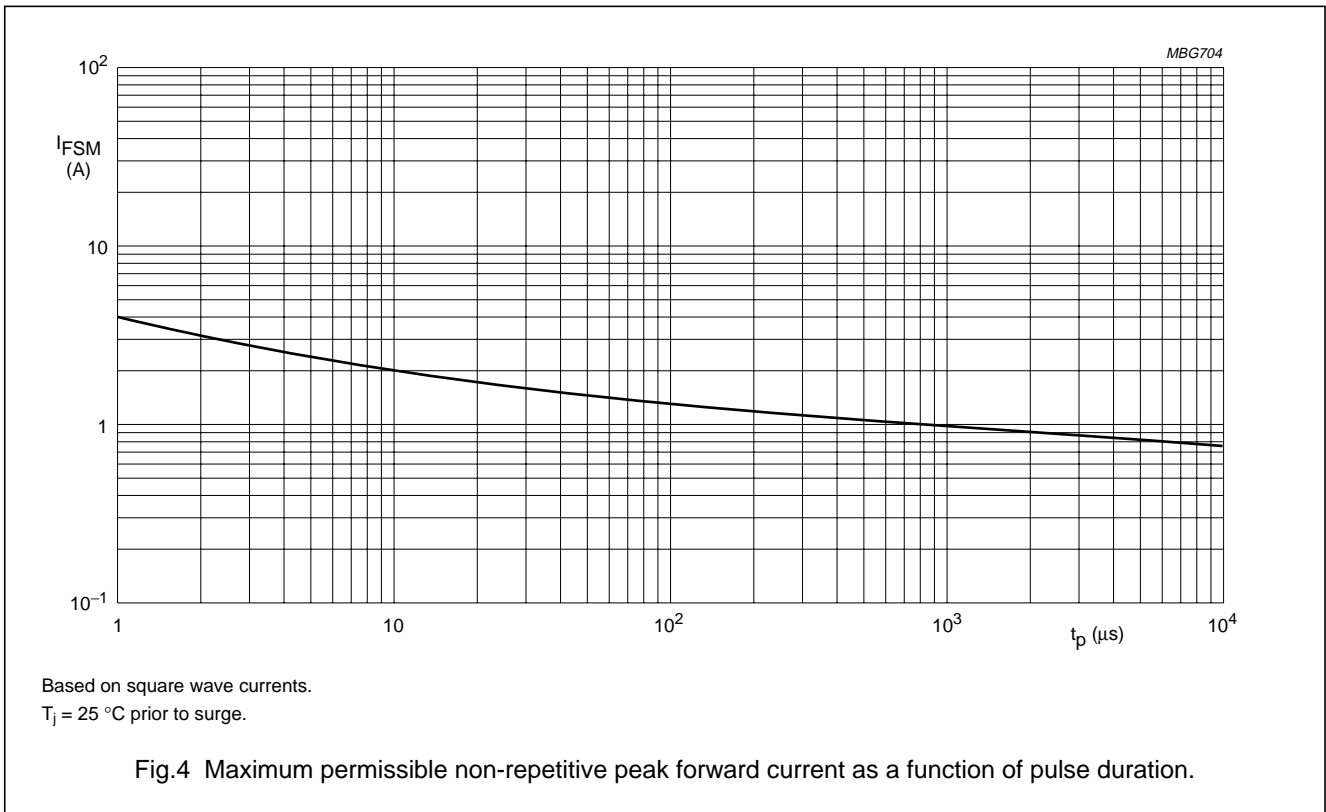
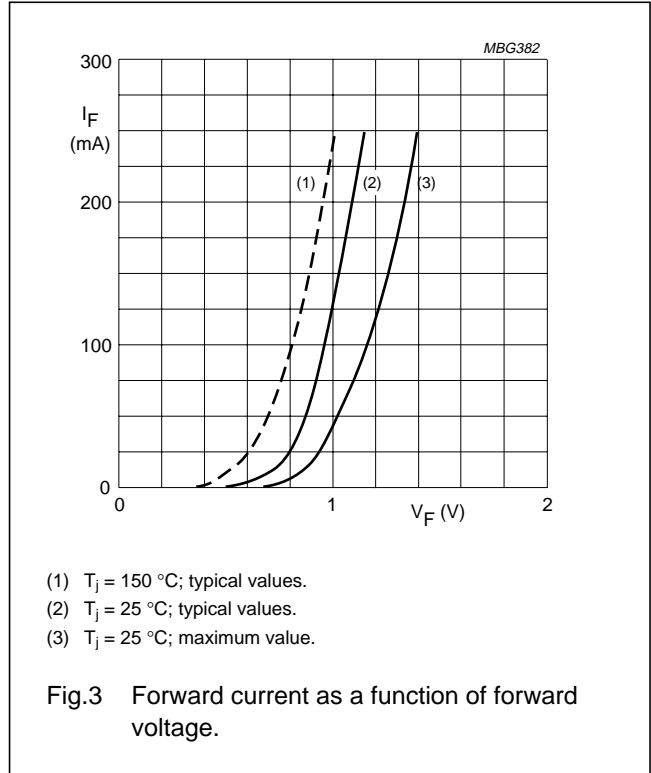
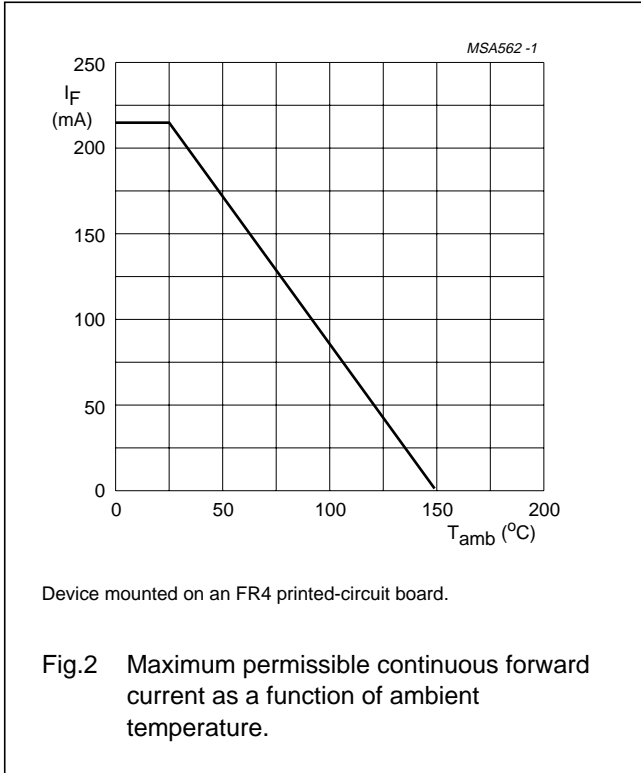
Soldering

Reflow soldering is the only recommended soldering method.

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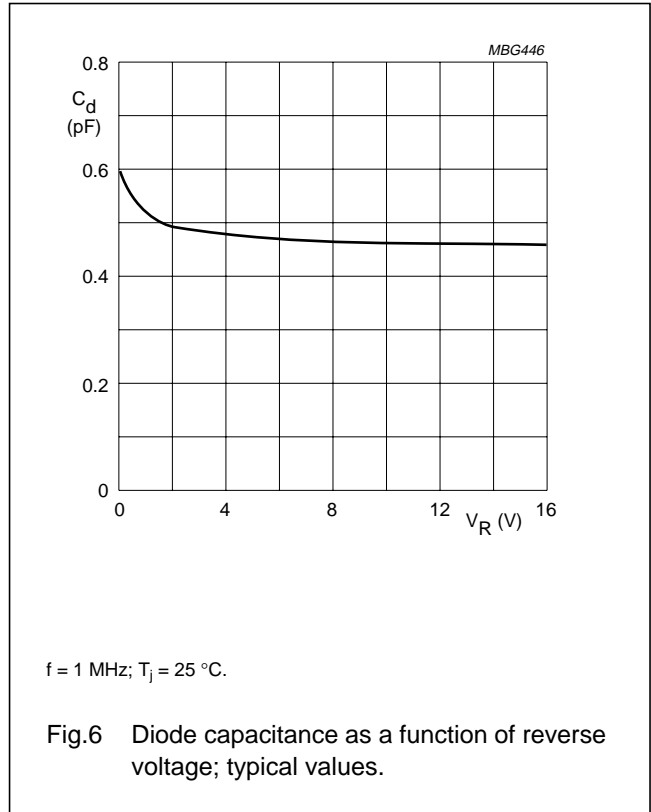
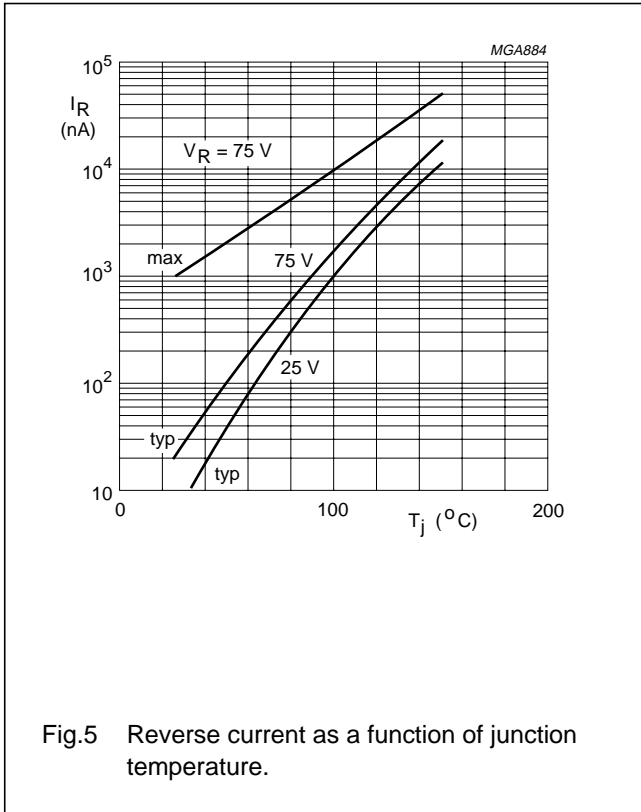
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GRAPHICAL DATA



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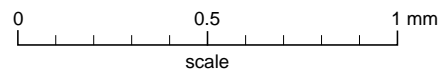
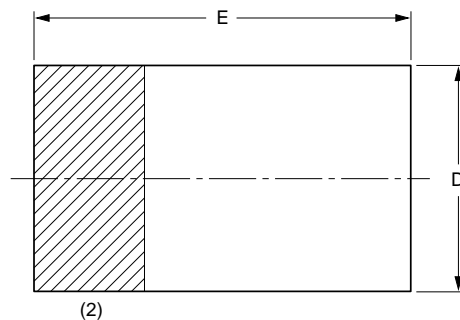
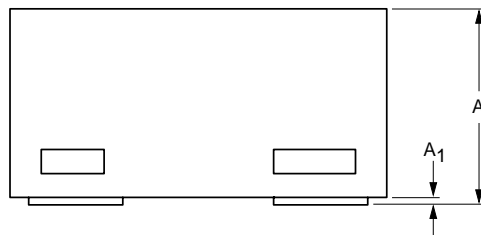
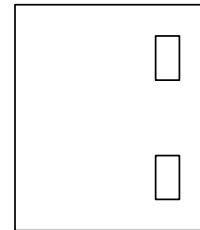
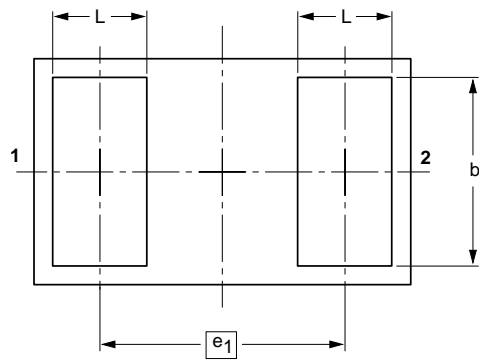
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PACKAGE OUTLINE

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾	A ₁ max.	b	D	E	e ₁	L
mm	0.50 0.46	0.03	0.55 0.47	0.62 0.55	1.02 0.95	0.65	0.30 0.22

Notes

- Including plating thickness
- The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD882						03-04-16 03-04-17

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
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